ABSOCIATION CONNECTING ELECTRONCE INDUSTRIES INDUSTRIES INTERNITION CONNECTING	annockburn, Illinois. A	All rights reserved un ntions.	nder both	This docume level parts, t	ent is a declaration	ion of the s encompasse	ubstances s all lowe	within the manufactu r level materials for w	rer listed in which the m	tem. Note: it nanufacturer	f the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form 7 http://www.ipc.org/IPC-175x Distribution			e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information					
Supplier Information													
Company name* Company unique ID			Uniqu			nique ID Authority				Response Date*			
semi									2024-05-10				
Contact Name	tet Name Title - Contact]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	luct-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com						
ithorized Representative* Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Number M	Ifr Item Number	Mfr Item Name		·	Effective Date	e Version]	Manufacturing Site		Weight*	UOM	Unit Type	
N	CP1615C4DR2G High Voltage High Controller		h Efficiency PFO	С	2024-05-10 PH1		PH1	-	140.01	mg	Each		
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material	I Terminal Base Alloy		-STD-020 MSL	Rating	Peak Pro	Process Body Temperature Max Time at Peak		Temperature Number of		er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU Alloy 1		1		260		С	30	secon	ds 3				
Comments													
level 1 - maximum time at peak temperature du	ring soldering is 10-3	0 seconds											
For more information regarding material comp	osition please refer to	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.05	mg	Supplier	Silicon (Si)	7440-21-3		3.05	mg
Die Attach	4.85	mg	Supplier	Organic peroxide	3006-86-8		0.0364	mg
			Supplier	Diluent B	Proprietary Data		0.2425	mg
			Supplier	Diluent A	Proprietary Data		0.194	mg
			Supplier	Dicyandiamine	461-58-5		0.0121	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.88	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.485	mg
Lead Frame	73.39	mg	Supplier	Silver (Ag)	7440-22-4		0.7339	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1468	mg
			Supplier	Iron (Fe)	7439-89-6		1.9081	mg
			Supplier	Copper (Cu)	7440-50-8		70.6012	mg
Mold Compound-Black	55.11	mg		Epoxy resin	proprietary data		3.8577	mg
			Supplier	Phenolic Resin	Proprietary Data		1.3778	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.1333	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2756	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		44.088	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		1.3778	mg
lating	3.5	mg	Supplier	Tin (Sn)	7440-31-5		3.5	mg
Wire Bond	0.11	mg	Supplier	Palladium (Pd)	7440-05-3		0.0023	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.1074	mg